

Customer No.: 31561
Docket No.: 11182-US-PA
Application No.: 10/710,582

REMARKS

Present Status of the Application

Applicant appreciates that claims 1, 2 and 8 are considered to be allowable.

The Office Action rejects claim 1 under 35 U.S.C. 112, first paragraph. Applicant has amended independent claim 1. After entry of the amendments, claims 1-2 and 8 remain pending in the present application, and reconsideration of those claims is respectfully requested.

Discussion of Claim Rejections under 35 USC 112

As for example shown in FIG. 6 and FIG. 7A, the substrate core layer 204 of the substrate 200 is removed due to the singulating the substrate 200 for separating the chip 208. Therefore, the features recited in currently amended claim 1 are well supported by the specification.

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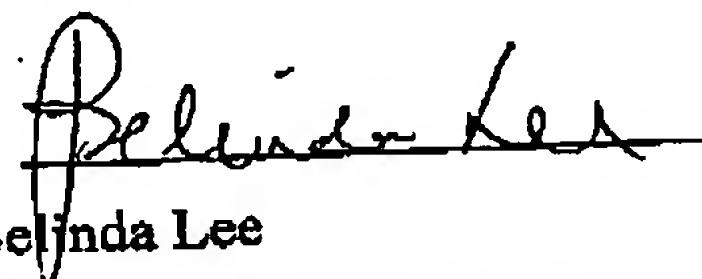
CONCLUSION

For at least the foregoing reasons, it is believed that all the pending claims 1-2 and 8 are in proper condition for allowance. If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date :

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